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United States Patent [19]
Klinker

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[54] **INDENTED PORTION OF A PROCESSOR PACKAGE COVER PLATE**

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[73] Assignee: **Intel Corporation**, Santa Clara, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **29/073,233**

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[51] **LOC (6) Cl.** **14-02**

[52] **U.S. Cl.** **D14/114**

[58] **Field of Search** D14/100, 114,
D14/121; 438/107; D21/48; 360/97.01-99.12;
361/737, 752, 715-21, 728, 730, 732

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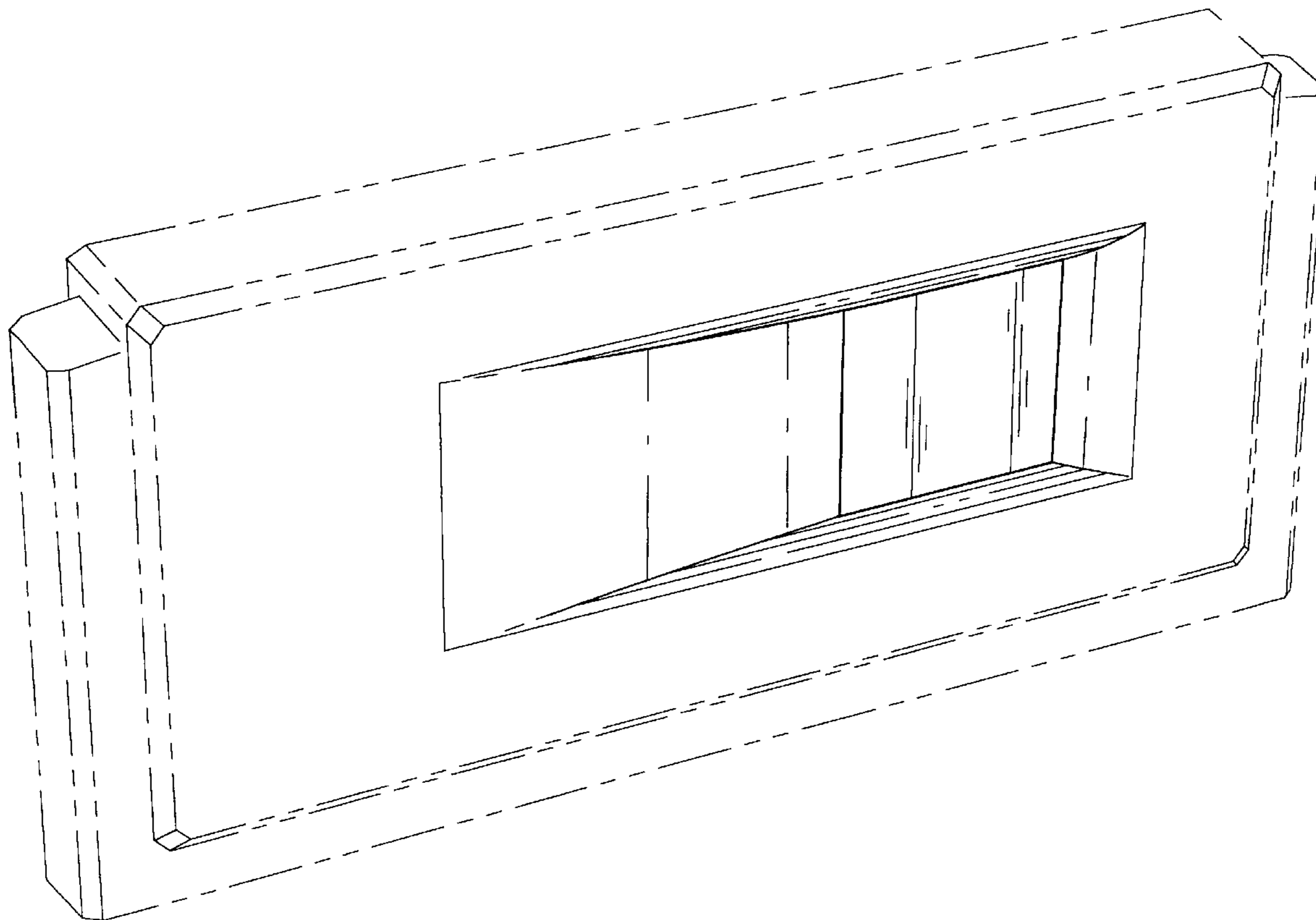
[57] **CLAIM**

The ornamental design for an indented portion of a processor cover plate, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an indented portion of a processor package cover plate; and, FIG. 2 is a front view thereof. The broken line drawing of a processor package in both views is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 2 Drawing Sheets



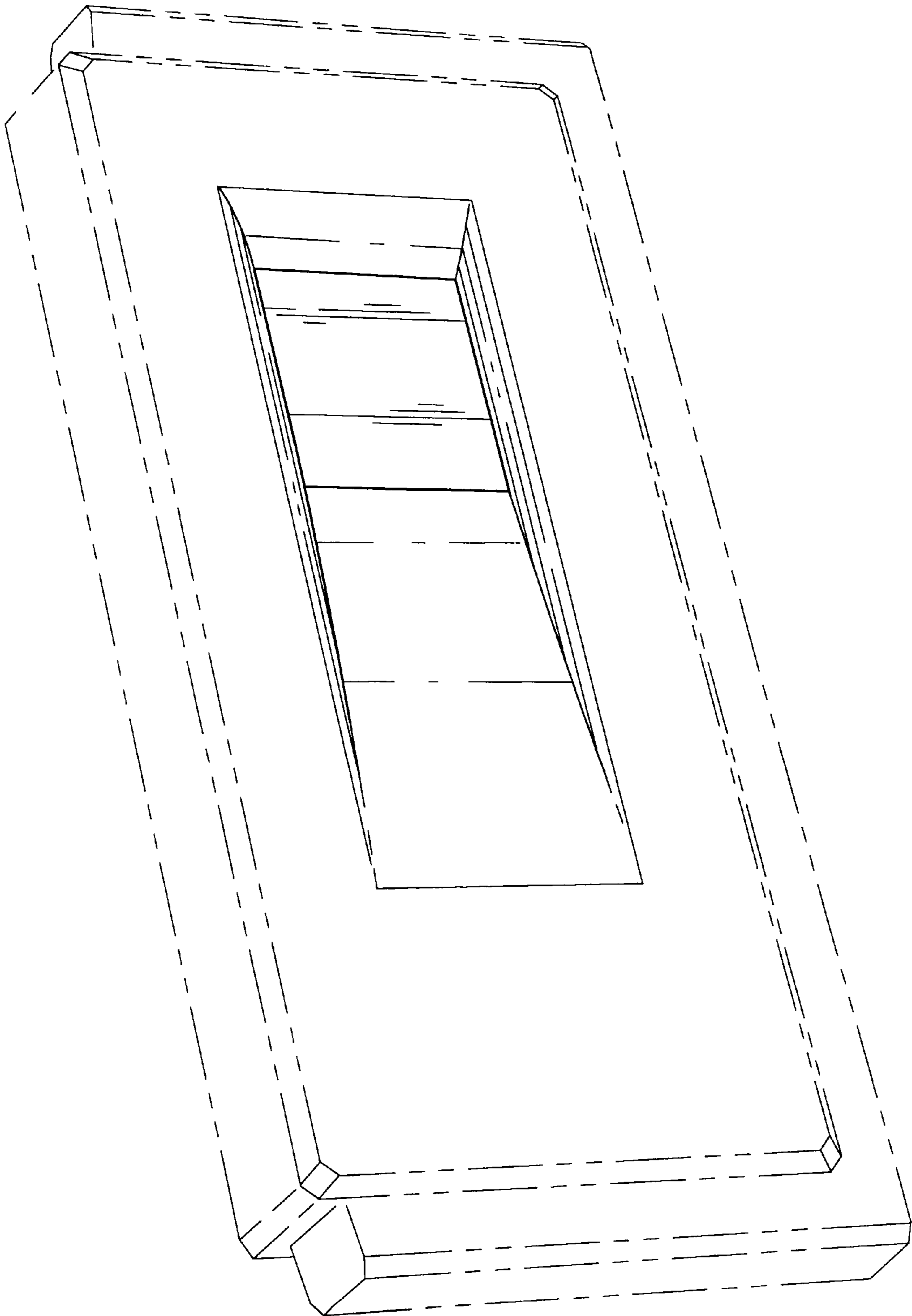


FIG. 1

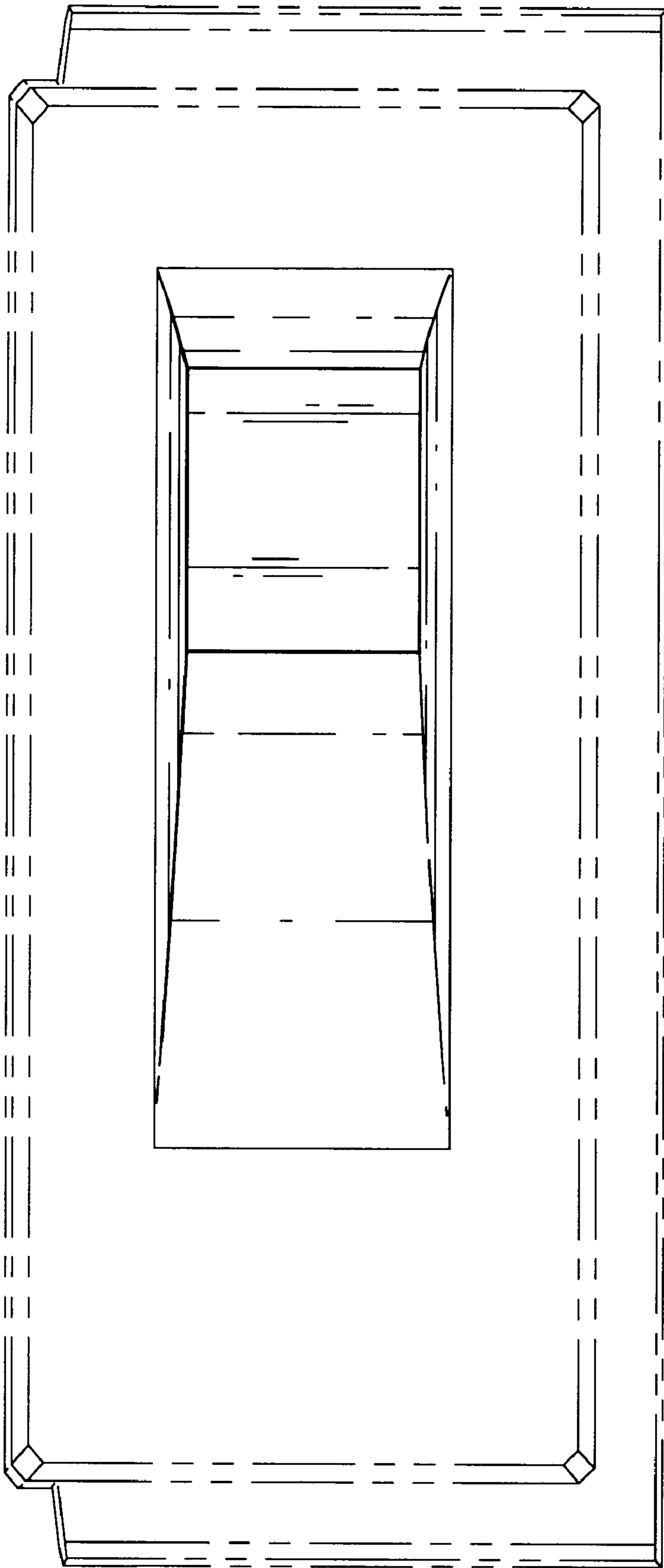


FIG. 2